Specification of Thermoelectric Module

TEHC1-12706

Description

The 127 couples, 40 mm × 40 mm size single module which is made of our high performance ingot to achieve superior cooling performance and 74 ℃ or larger delta Tmax, is designed for superior cooling and heating applications. Beyond the standard below, we can design and manufacture the custom made module according to your special requirements.

Features

- High effective cooling and efficiency.
- No moving parts, no noise, and solid-state
- Compact structure, small in size, light in weight
- Environmental friendly, RoHS compliant
- Precise temperature control
- Exceptionally reliable in quality, high performance

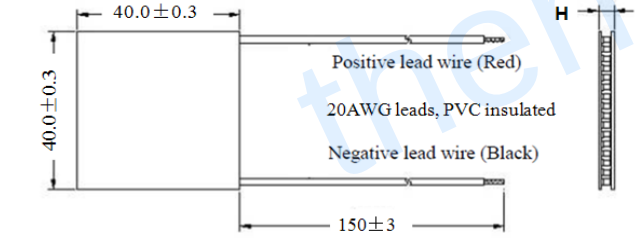
Application

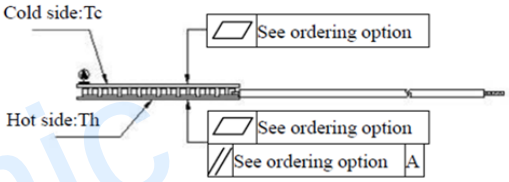
- Food and beverage service refrigerator
- Portable cooler box for cars
- Temperature stabilizer
- Liquid cooling
- CPU cooler and scientific instrument
- Photonic and medical systems

Performance Specification Sheet

Th(℃)	27	50	Hot side temperature at environment: dry air, N_2
DT_{max}(℃)	74	83	Temperature Difference between cold and hot side of the module when cooling capacity is zero at cold side
U_{max}(Voltage)	16.8	18.08	Voltage applied to the module at DT_{max}
I_{max}(amps)	6.3	6.3	DC current through the modules at DT_{max}
Q_{Cmax}(Watts)	66	73.6	Cooling capacity at cold side of the module under DT=0 ℃
AC resistance(ohms)	2.05	2.25	The module resistance is tested under AC
Tolerance (%)	±10		For thermal and electricity parameters

Geometric Characteristics Dimensions in millimeters





Manufacturing Options

A. Solder:

1. T100: BiSn (Melting Point=138 ℃)
2. T200: CuSn (Melting Point=227 ℃)

B. Sealant:

1. NS: No sealing (Standard)
2. SS: Silicone sealant
3. EPS: Epoxy sealant
4. Customer specify sealing

C. Ceramics:

1. AlO :Alumina (Al_2O_3, white 96%)
2. AlN :Aluminum Nitride
3. AL : Aluminum substrate

D. Ceramics Surface Options:

1. Blank ceramics (not metalized)
2. Metalized (Copper-Nickel plating)

Ordering Option

Suffix	Thickness (mm)	Flatness/ Parallelism (mm)	Lead wire length(mm) Standard/Optional length
TF	0:3.8±0.1	0:0.05/0.05	150±3/Specify
TF	1:3.8±0.05	1:0.025/0.025	150±3/Specify
TF	2:3.8±0.025	2:0.015/0.015	150±3/Specify
Eg. TF01: Thickness 3.8±0.1(mm) and Flatness 0.025/0.025 (mm)			

Naming for the Module

TEHC1-12706- X-X - X - X

- Ceramics
- Flatness/ Parallelism
- Sealant
- Solder

TEHC1-12706–T100 -NS –TF01 -AlO

T100: BiSn(Tmelt=138℃)

NS: No sealing

AlO: Alumina white 96%

TF01: Thickness ±0.15 (mm) and Flatness/Parallelism 0.08/0.13(mm)

Tel: +86-791-88198288 Fax: +86-791-88198308 Email: sales@thermonamic.com.cn Web Site: www.thermonamic.com.cn

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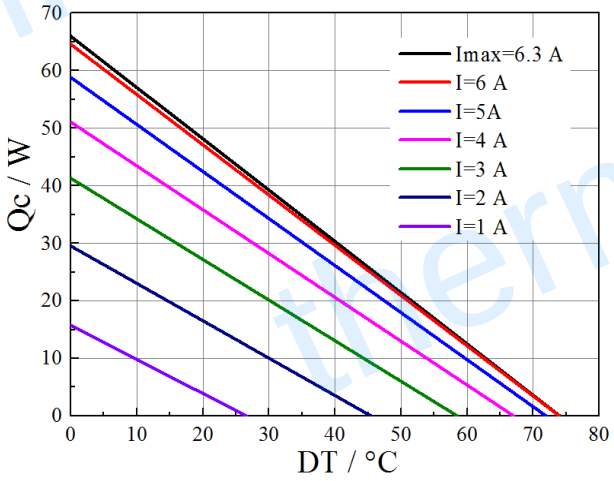
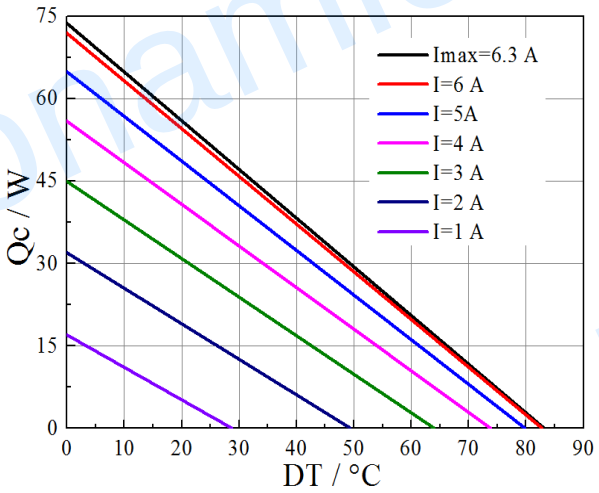
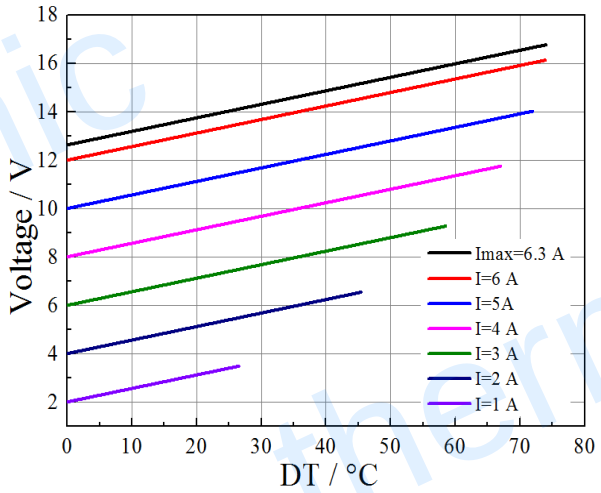
Performance Curves at Th=27 ℃

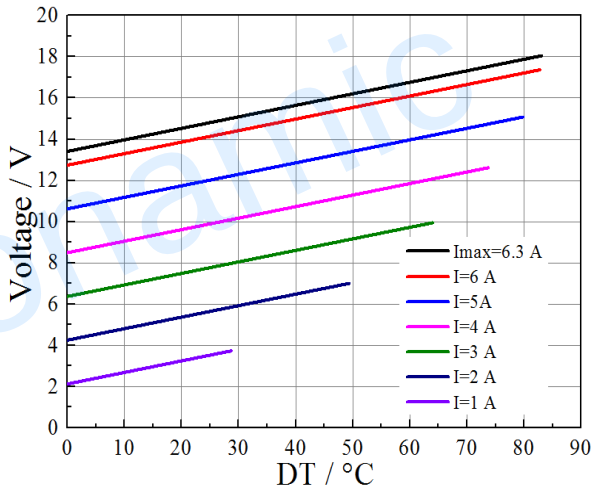


Performance Curves at Th=50 ℃

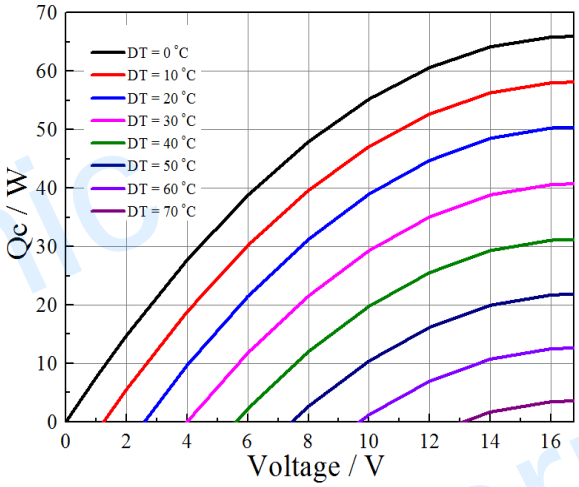


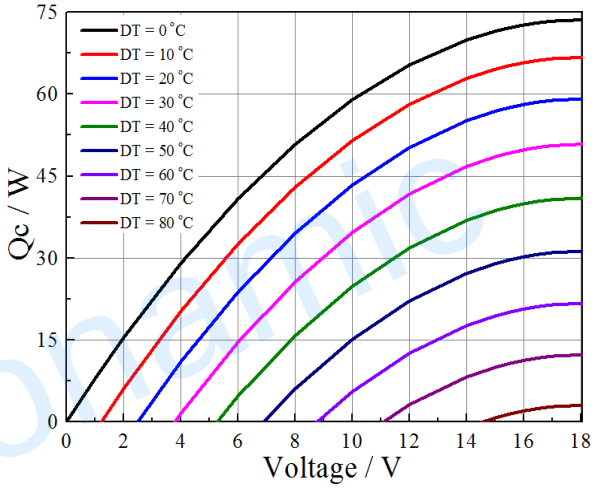
Standard Performance Graph Qc= f(DT)





Standard Performance Graph V= f(DT)





Standard Performance Graph Qc= f(V)

Specification of Thermoelectric Module

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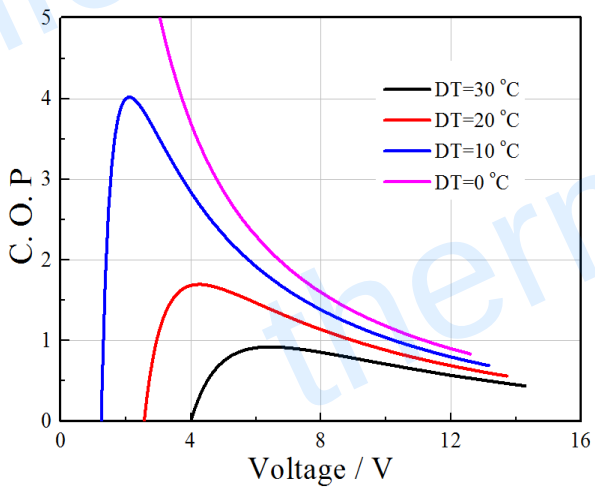
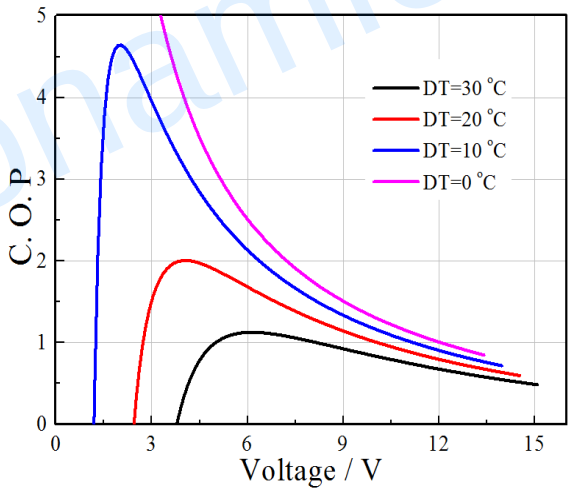
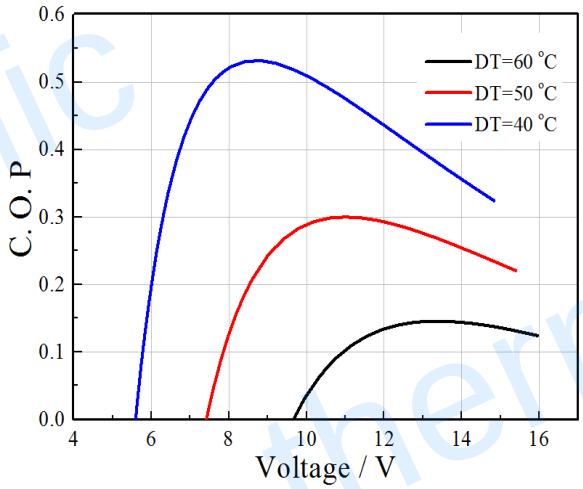
Performance Curves at Th=27 ℃

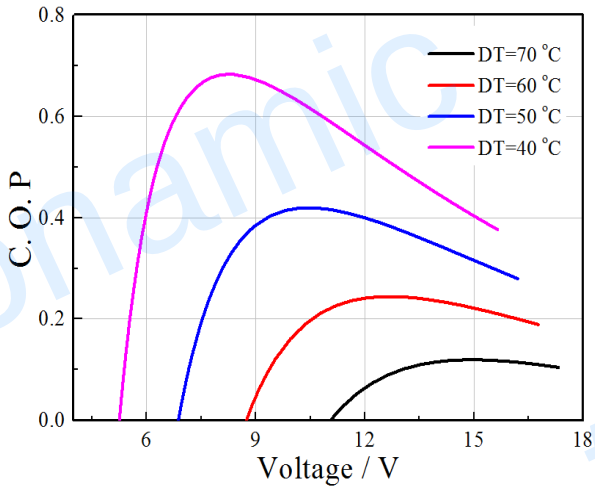


Performance Curves at Th=50 ℃



Standard Performance Graph COP = f(V) of ΔT ranged from 0 to 30 ˚C





Standard Performance Graph COP = f(V) of ΔT ranged from 40 to 60/70 ˚C

Remark: The coefficient of performance (COP) is the cooling power Qc/Input power (V ×I).

Operation Cautions

- Attach the cold side of module to the object to be cooled
- Attach the hot side of module to a heat radiator for heat dissipating
- Operation or storage module below 100 ℃
- Operation below I_{max} or V_{max}
- Work under DC

Note: All specifications subject to change without notice.